



Material Composition Declaration

EPC2033

Company Name	Efficient Power Conversion (EPC)	Issue Date:	3/14/2018
Contact Name:	Yanping Ma	Contact Title:	VP Quality
Contact Phone:	(310) 615-0283	Contact Email:	yanping.ma@epc-co.com
Part Weight:	18.7 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)	(%)	(ppm)
Chip	Silicon	7440-21-3	13.9274	74.6654	77.75	746654
	Silicon oxide	7631-86-9	0.0745	0.3993		3993
	Silicon nitride	12033-89-5	0.0271	0.1452		1452
	Gallium nitride	25617-97-4	0.1285	0.6887		6887
	Aluminum	7429-90-5	0.1433	0.7683		7683
	Aluminum nitride	24304-00-5	0.0379	0.2033		2033
	Titanium	7440-32-6	0.0031	0.0165		165
	Titanium nitride	25583-20-4	0.0125	0.0673		673
	Copper	7440-50-8	0.0048	0.0256		256
	Tungsten	7440-33-7	0.0038	0.0205		205
	Polyimide		0.1403	0.7524		7524
Under Bump Metal	Titanium	7440-32-6	0.0017	0.0091	0.77	91
	Nickel	7440-02-0	0.0000	0.0000		0
	Vanadium	7440-62-2	0.0000	0.0000		0
	Copper	7440-50-8	0.1417	0.7595		7595
Solder Bump	Tin	7440-31-5	3.8262	20.5125	21.48	205125
	Silver	7440-22-4	0.1603	0.8592		8592
	Copper	7440-50-8	0.0200	0.1074		1074
Sum in total:			18.6531	100.0000	100	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.